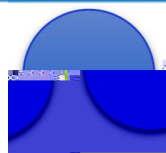
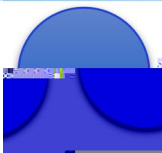


2016 白光 1W 贴片式发光二极管



目录
Catalogue



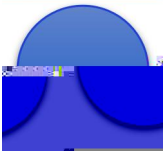
Parameter	Symbol	Value	Unit
Max Power Dissipation	PD	1000	mW
Max Continuous Forward Current	IF	350	mA
Peak Forward Current	IFP	500	mA
Max Reverse Voltage	VR	5	V
Antistatic ability	ESD	2000	V
Operating Temperature Range	TOPR	-40 ~ +85 C	
Storage Temperature Range	TSTR	-40 ~ +85 C	
/ Lead Soldering Temperature/Time	TSOL	260 ≤ 6S	/

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test conditions
Luminous Intensity	Φ	90	100	130	LM	IF=350mA
Color temperature	TC	6000		6500	K	IF=350mA
Coordinate value	X					IF=350mA
	Y					IF=350mA
Forward Voltage	VF	2.8		3.4	V	IF=350mA
Color rendering index	Ra		70			IF=350mA
Viewing Angle	2 θ 1/2		120		Deg	IF=350mA
Reverse Current	IR			1	μ A	VR=5V



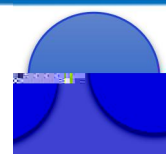
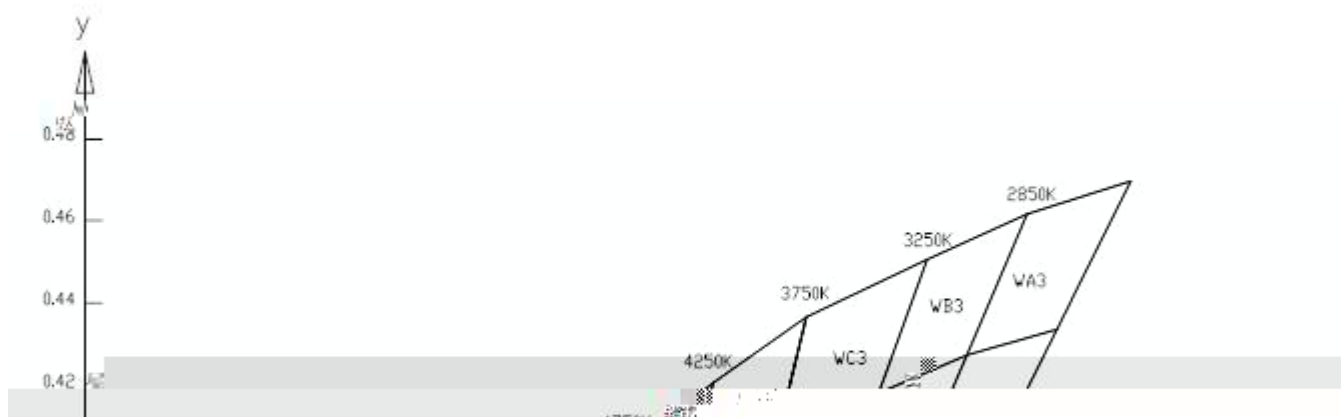
亮度分档

:

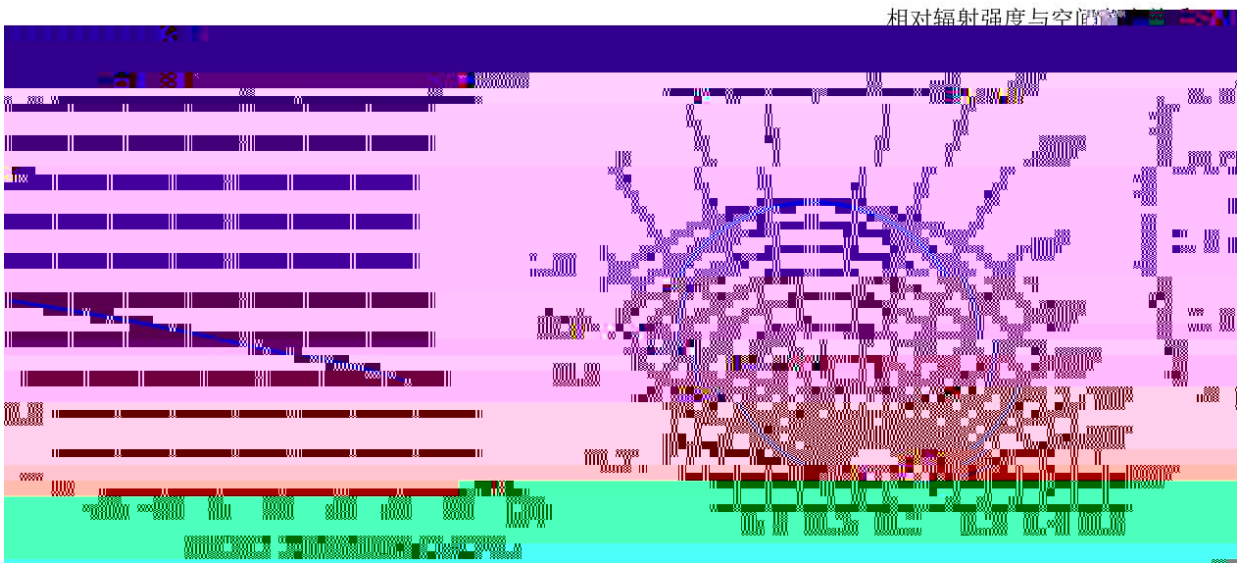
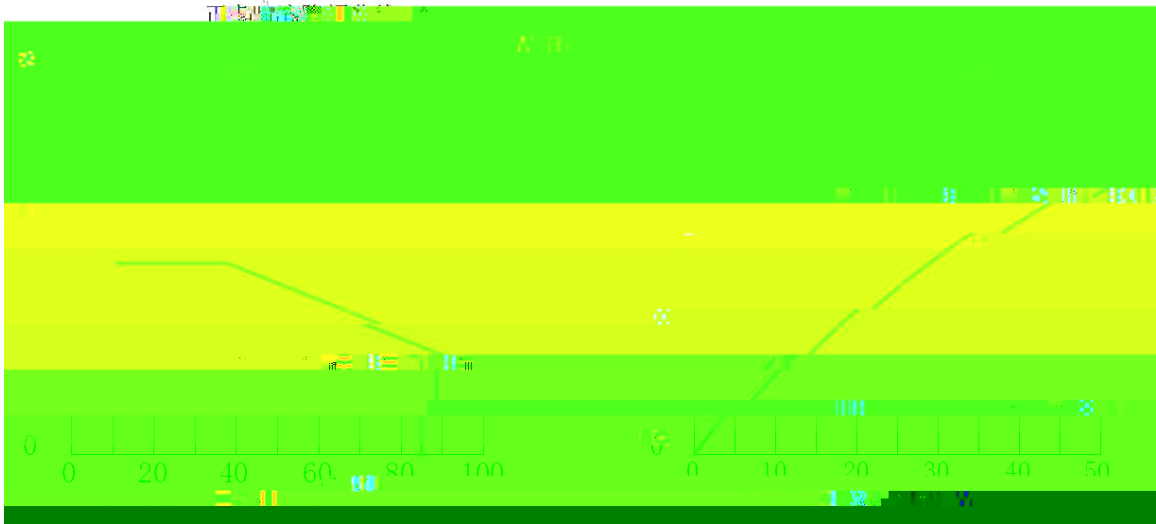
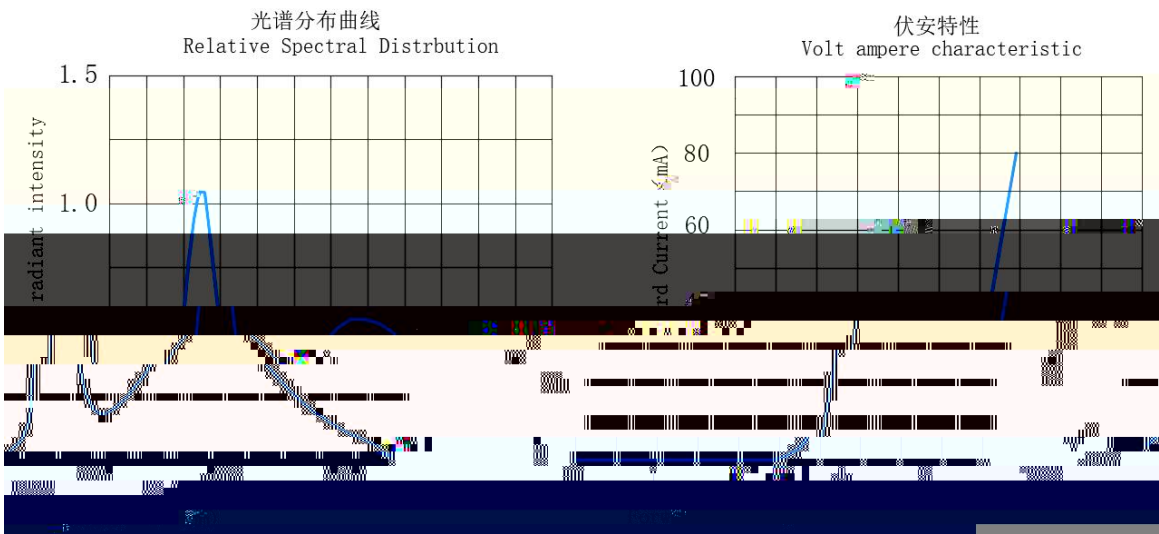


Typical photoelectricity characteristic curve chart

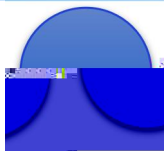
CIE 1931 xy CHROMATICITY DIAGRAM



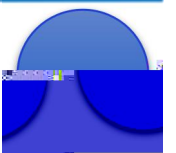
典型特性曲线

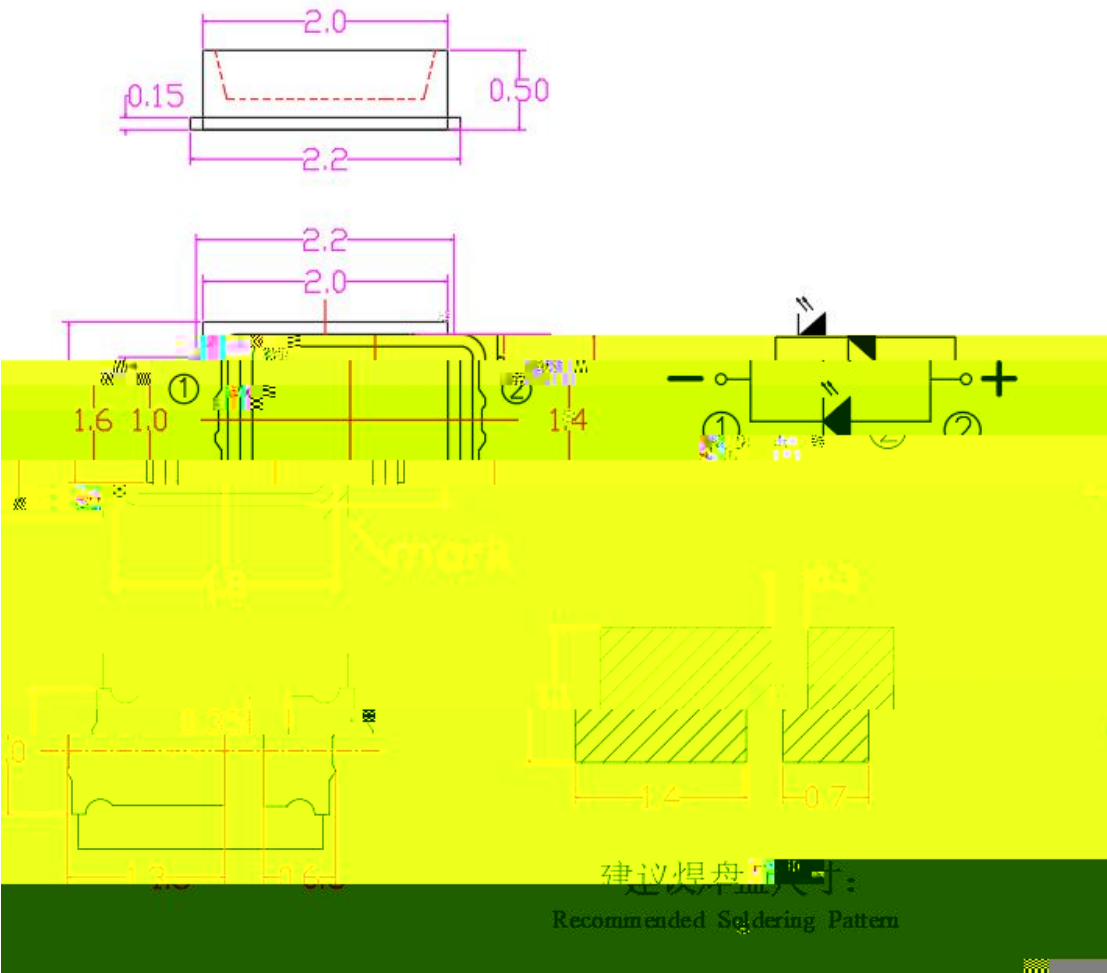


2505 /Note If not otherwise indicated the test environment temp erature is 2505



dinghi

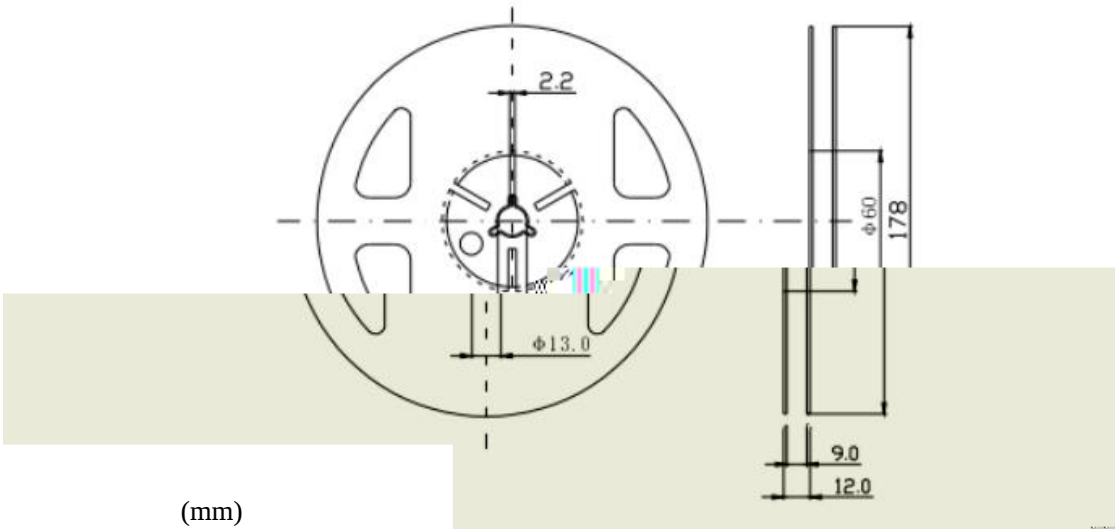




- Remarks:
1. All dimensions are in millimeters.
 2. Tolerance is $\pm 0.25\text{mm}$ unless otherwise noted

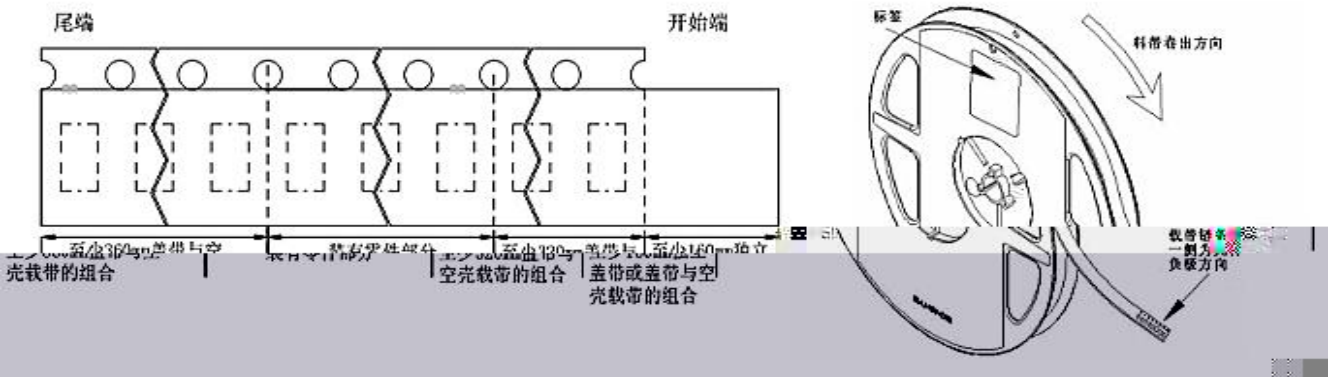
包装 ()

载带与圆盘尺寸

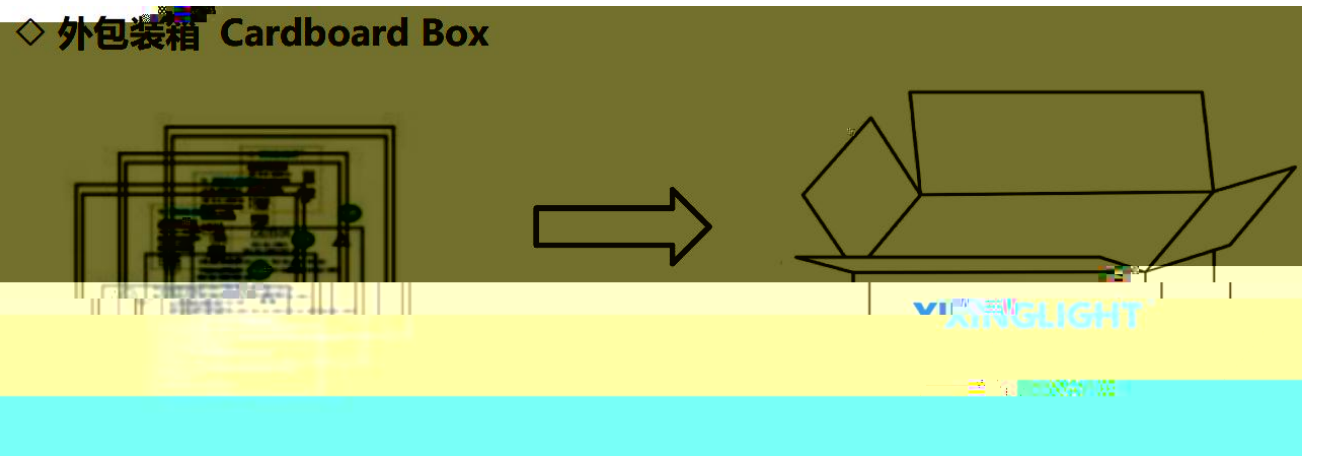


1. (mm)
1. Size unit is mm (mm).
2. 0.1mm
2. The dimensional tolerance is 0.1mm.

圆盘及载带卷出方向及空穴规格 Disk and carrier belt direction of roll and hole dimensions



包装（ ）



焊接指导 ()

使用烙铁手工焊接

20W

300

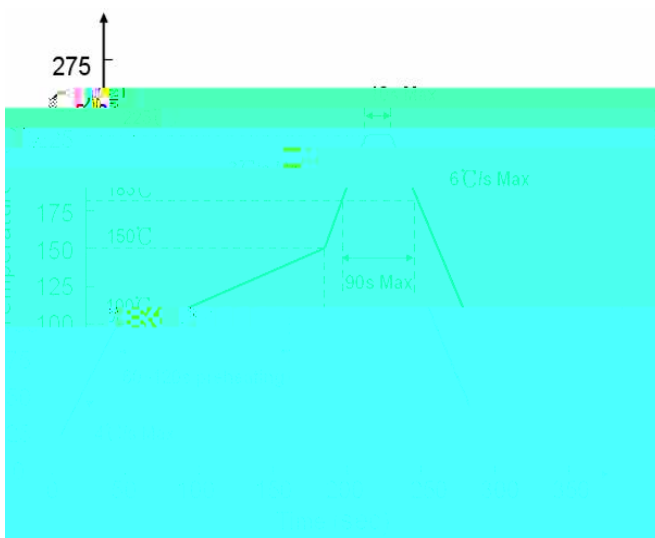
3

LED

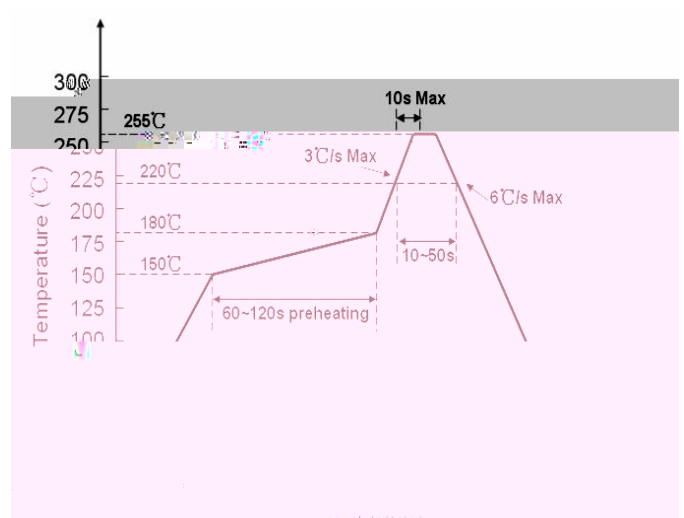
A soldering iron of less than 20W is recommended to be used in Hand Soldering. Please keep the temperature of the soldering iron under 300 while soldering. Each terminal of the LED is to go for less than 3 second and for one time only. Be careful because the damage of the product is often started at the time of the hand soldering.

回流焊接

Use the conditions shown in the under Figure of Pb-Free Reflow Soldering.



Lead process



lead free

Reflow soldering should not be done more than two times.

LED

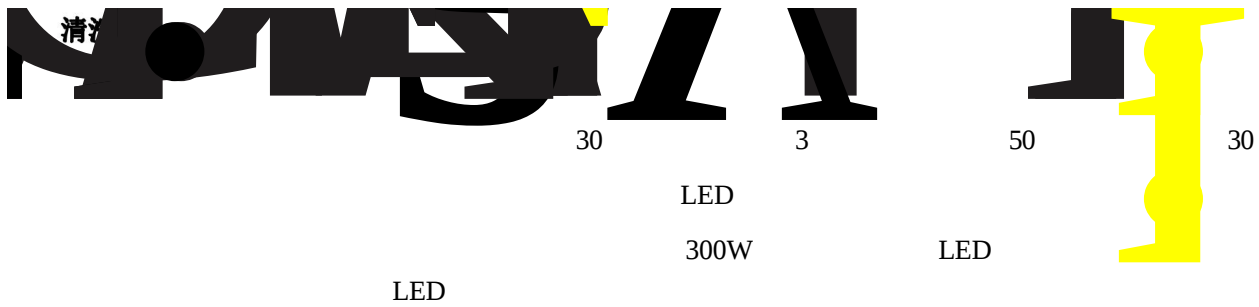
Stress on the LEDs should be avoided during heating in soldering process.

After soldering, do not deal with the product before its temperature drop down to room temperature.

240 ± 5 /6S

The recommended maximum welding temperature for the product is 240 ± 5 /6s

焊接指导 ()



It is recommended that alcohol be used as a solvent for cleaning after soldering. Cleaning is to go u 30 for 3 minutes or 50 for 30 seconds. When using other solvents, it should be confirmed beforehand whether the solvents will dissolve the package and the resin or not.

Ultrasonic cleaning is also an effective way for cleaning. But the influence of Ultrasonic cleaning on LED depends on factors such as ultrasonic power. Generally, the ultrasonic power should not be higher than 300W. Before cleaning, a pretest should be done to confirm whether any damage to LEDs will occur.

* 注意: PCB

PCB

* This general guideline may not apply to all PCB designs and configurations to 1 1 1 1 —

A

LED ,W

V_F

LED

B

LED

* In designing a circuit, the current through each LED must not exceed the absolute maximum rating specified for each LED. In the meanwhile, resistors for protection should be applied, otherwise slight voltage shift will cause big current change, burn out may happen.

It is recommended to use Circuit A which regulates the current flowing through each

